

1.5MHz 600mA, Synchronous Step-Down Regulator

General Description

EML3406 is designed with high efficiency step down DC/DC converter for portable devices applications. It features with extreme low quiescent current with no load which is the best fit for extending battery life during the standby mode. The device operates from 2.5V to 6.0V input voltage and up to 600mA output current capability. High 1.5MHz internal frequency makes small surface mount inductors and capacitors possible and reduces overall PCB board space. Further, build-in synchronous switch makes external Schottky diode is no longer needed and efficiency is improved. EML3406 is designed base on pulse width modulation (PWM) for low output voltage ripple and fixed frequency noise, low dropout mode provides 100% duty cycle operation. Low reference voltage is designed for achieving regulated output down to 0.6V.

The device is available in an adjustable version and fixed output voltages of 1.2V, 1.5V, 1.8V and 3.3V. The EML3406 is available in SOT-25 package.

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Features

- Achieve 95% efficiency
- Input Voltage: 2.5V to 6.0V
- Output Current up to 600mA
- Reference voltage 0.6V
- Quiescent Current 200µA with No Load
- Internal switching frequency 1.5MHz
- No Schottky Diode needed
- Low Dropout Operation: 100% Duty Cycle
- Shutdown current < 1µA
- Excellent Line and Load Transient Response
- Over-temperature Protection

Applications

- Blue-Tooth devices
- Cellular and Smart Phones
- Personal multi-media Player (PMP)
- Wireless networking
- Digital Still Cameras
- Portable applications

Typical Application (adjustable)

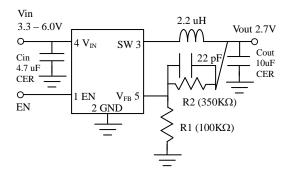


Fig. 1

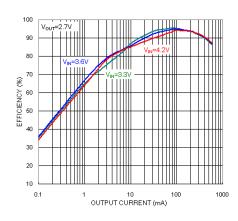
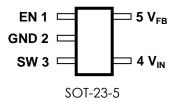


Fig. 2



CONNECTION DIAGRAM



ORDER INFORMATION

EML3406-XXVF05GRR

XX Output voltage

VF05 SOT-23-5 Package

GRR RoHS Package

Rating: -40 to 85°C

Package in Tape & Reel

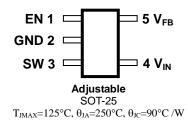
NRR RoHS & Halogen free package (By Request)

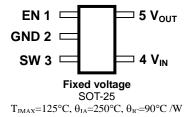
Order, Mark & Packing Information

Packago	Vout	Product ID	Product ID Marking New Old		Packing	
Package	V 0 0 1	FIOGUCTID			racking	
	1.2	EML3406-12VF05GRR		L601		
	1.2		× K	Date code	l	
SOT-23-5	1.5 EML3406	EML3406-15VF05GRR	15 V	L604		
		LWL5400-15V105GKK		Date code	Tape & Reel	
	1.8 EML3406-18VF05GRR	FMI 3404-18VF05GRR	3406 Tracking code	L607		
			Date code	3Kpcs		
	3.3	EML3406-33VF05GRR	MINI DOT LINI	L60M		
	0.0		LIVIED-400 GOVI GOOKK	3.3 EML3406-33VF05GRR NA GND	Date code	
SOT-23-5	adjustable EML3406-00VF05GR	FMI3404-00VF05GRR		L600		
			Date code			



Package configuration





Pin Functions

Pin#	Pin Name	Function	
		Enable Pin.	
1	EN	Minimum 1.2V to enable the device. Maximum 0.4V to shut down the	
		device. Do not leave this pin floating.	
2	GND	Ground Pin.	
		Switch Pin.	
3	SW	Must be connected to Inductor. This pin connects to the drains of the	
		internal main and synchronous power MOSFET switches.	
		Input voltage Pin.	
4	V_{IN}	Must be closely decoupled to GND pin with a 4.7µF or greater ceramic	
		capacitor.	
	W	Feedback Pin.	
	V _{FB}	Receives the feedback voltage from an external resistive divider across the	
-	(Adjustable)	output.	
5	V _{out}	Output Voltage Pin.	
	(Fixed	An internal resistive divider divides the output voltage down for comparison	
	voltage)	to the internal reference voltage.	

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Absolute Maximum Ratings

Devices are subjected to failure if they stay above absolute maximum ratings.

Input Voltage 0.3V to	6.5V
EN, V _{FB} Voltages 0.3V t	
SW Voltage $$	
PMOS Switch Source Current (DC) 80	
NMOS Switch Sink Current (DC) 80	
Peak Switch Sink and Source Current	

Operating Temperature Range -40°C t	o 85°C
Junction Temperature (Notes 1, 3)	
Storage Temperature Range 65°C to	150°C
Lead Temperature (Soldering, 10 sec)	240°C
ESD Susceptibility	
HBM	2KV
MM	-200V

Electrical Characteristics

The \bullet denotes specifications which apply over the full operating temperature range, otherwise specifications are $T_A = 25$ °C. $V_{IN} = 3.6$ V unless otherwise specified.

Symbol	Parameter	Conditions		Min	Тур	Max	Units
I _{VFB}	Feedback Current					±30	nA
V_{FB}	Regulated Feedback Voltage	T _A = 25°C		0.588	0.600	0.612	V
ΔV_{FB}	Reference Voltage Line Regulation	V _{IN} = 2.5V to 5.5V	•			0.4	%/V
V _{OUT} %	Output Voltage Accuracy		•	-3		3	%
		$\Delta V_{OVL} = V_{OVL} - V_{FB}$, EML3406			50		mV
ΔV_{OVL}	Output Over-voltage Lockout	$\Delta V_{OVL} = V_{OVL} - V_{OUT},$ EML3406-Fixed			7.8		%
ΔV _{OUT}	Output Voltage Line Regulation	V _{IN} = 2.5V to 5.5V	•			0.4	%/V
I _{PK}	Peak Inductor Current	$V_{IN} = 3V$, $V_{FB} = 0.5V$ or $V_{OUT} = 90\%$, Duty Cycle < 35%			1.0		А
V _{LOADREG}	Output Voltage Load Regulation				0.5		%
	Quiescent Current (Note 2)	V _{FB} = 0.5V or V _{OUT} = 90%			200	340	μA
Is	Shutdown	$V_{EN} = 0V$, $V_{IN} = 2.5V$ to $6.0V$			0.1	1	μΑ
£	Oscillator Frequency	V _{FB} = 0.6V or V _{OUT} = 100%	•	1.2	1.5	1.8	MHz
f _{OSC}		$V_{FB} = 0V$ or $V_{OUT} = 0V$	•		290		kHz
R _{PFET}	R _{DS(ON)} of PMOS	I _{SW} = 100mA			0.45	0.55	Ω
R _{NFET}	R _{DS(ON)} of NMOS	$I_{SW} = -100 \text{mA}$			0.40	0.5	Ω
I _{LSW}	SW Leakage	$V_{EN} = 0V$, $V_{SW} = 0V$ or 6.0V, $V_{IN} = 6.0V$				±1	μA
VEN	Enable Threshold		•	1.2			V
	Shutdown Threshold		•			0.4	V
I _{EN}	EN Leakage Current	V _{IN} = 2.5V to 6.0V	•			±1	μΑ

Note 1: T_J is a function of the ambient temperature T_A and power dissipation P_D ($T_J = T_A + (P_D)(250^{\circ}C/W)$)

Note 2: Dynamic quiescent current is higher due to the gate charge being delivered at the switching frequency.

Note 3: This IC is build-in over-temperature protection to avoid damage from overload conditions.

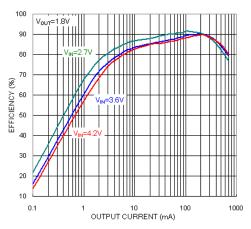
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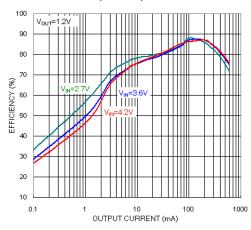
Typical Performance Characteristics

 $T_A = 25$ °C. $V_{IN} = 3.6V$ unless otherwise specified.

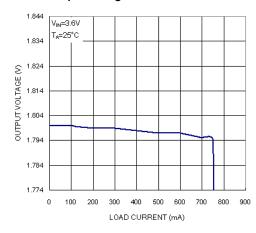
Efficiency vs Output Current



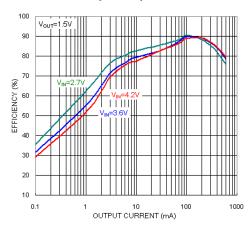
Efficiency vs Output Current



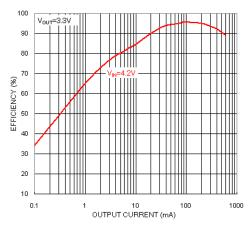
Output Voltage vs Load Current



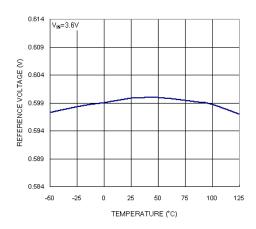
Efficiency vs Output Current



Efficiency vs Output Current



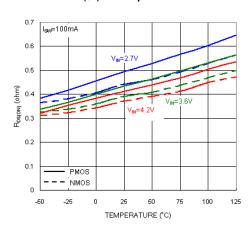
Reference voltage vs Temperature



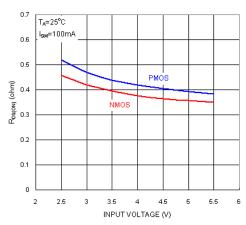
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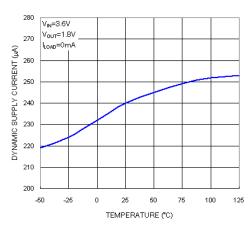
R_{DS(ON)} vs Temperature



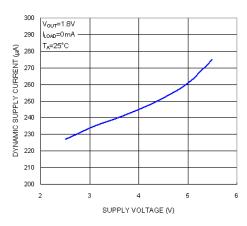
$R_{DS(ON)}$ vs Input Voltage



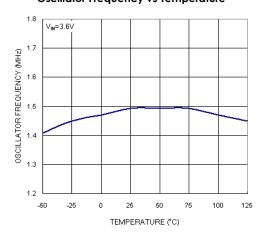
Dynamic Supply Current vs Temperature



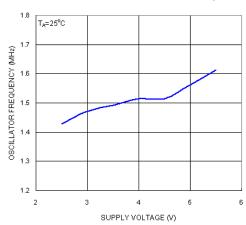
Dynamic Supply Current vs Supply Voltage



Oscillator Frequency vs Temperature



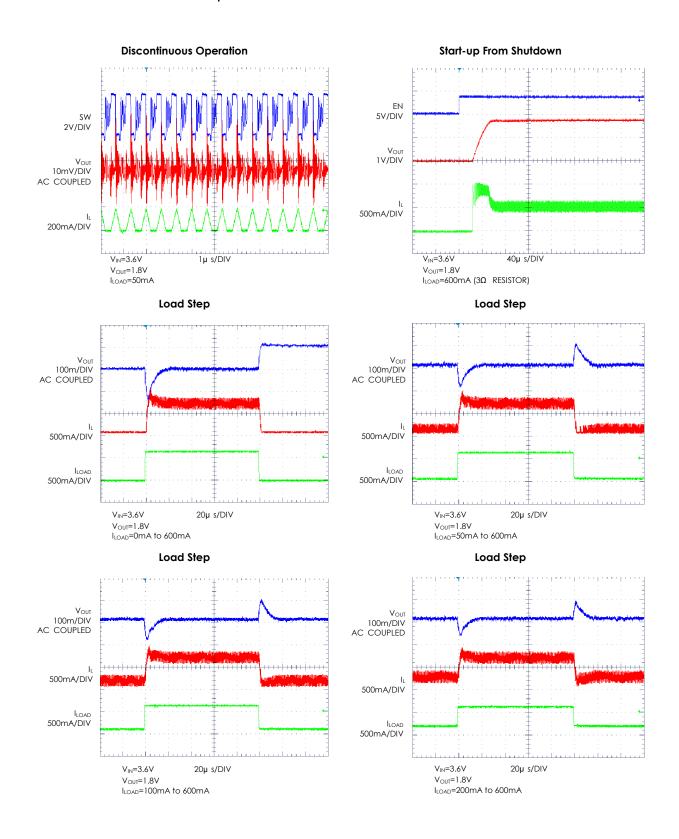
Oscillator Frequency vs Supply Voltage





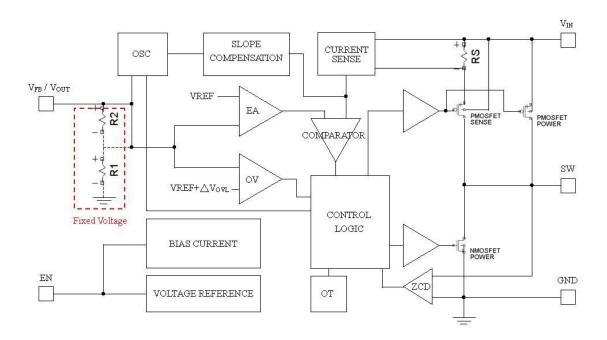
Typical Performance Characteristics

 $T_A = 25$ °C. $V_{IN} = 3.6V$ unless otherwise specified.





Functional Block Diagram

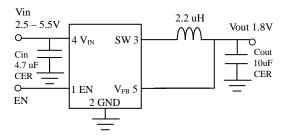




Applications

The typical application circuit of adjustable version is shown in Fig.1.

Fixed voltage version is shown below:



Inductor Selection

Basically, inductor ripple current and core saturation are two factors considered to decide the Inductor value.

$$\Delta I_{L} = \frac{1}{f \cdot L} V_{OUT} \left(1 - \frac{V_{OUT}}{V_{IN}} \right)$$
 Eq. 1

The Eq. 1 shows the inductor ripple current is a function of frequency, inductance, Vin and Vout. It is recommended to set ripple current to 40% of max. load current. A low ESR inductor is preferred.

CIN and COUT Selection

A low ESR input capacitor can prevent large voltage transients at V_{IN} . The RMS current of input capacitor is required larger than I_{RMS} calculated by:

$$I_{RMS} \cong I_{OMAX} \frac{\sqrt{V_{OUT}(V_{IN} - V_{OUT})}}{V_{IN}}$$
 Eq. 2

ESR is an important parameter to select C_{OUT} . The output ripple V_{OUT} is determined by:

$$\Delta V_{OUT} \cong \Delta I_{L} \left(ESR + \frac{1}{8 \cdot f \cdot C_{OUT}} \right)$$
 Eq. 3

Higher values, lower cost ceramic capacitors are now available in smaller sizes. These ceramic capacitors have high ripple currents, high voltage ratings and low ESR that make them ideal for switching regulator applications. Optimize very low output ripple and small circuit size is doable from Cout selection since Cout

does not affect the internal control loop stability. It is recommended to use the X5R or X7R which have the best temperature and voltage characteristics of all the ceramics for a given value and size.

Output Voltage (EML3406 adjustable)

In the adjustable version, the output voltage can be determined by:

$$V_{OUT} = 0.6 V \left(1 + \frac{R_2}{R_1} \right)$$
 Eq. 4

Thermal Considerations

Although thermal shutdown is build-in in EML3406 that protect the device from thermal damage, the total power dissipation that EML3406 can sustain should be base on the package thermal capability. The formula to ensure the safe operation is shown in Note 1.

To avoid the EML3406 from exceeding the maximum junction temperature, the user will need to do some thermal analysis.

Guidelines for PCB Layout

To ensure proper operation of the EML3406, please note the following PCB layout guidelines:

- 1. The GND trace, the SW trace and the V_{IN} trace should be kept short, direct and wide.
- 2. V_{FB} pin must be connected directly to the feedback resistors. Resistive divider R_1/R_2 must be connected and parallel to the output capacitor C_{OUT} .
- 3. The Input capacitor C_{IN} must be connected to pin V_{IN} as closely as possible.
- 4. Keep SW node away from the sensitive V_{FB} node since this node is with high frequency and voltage swing.
- 5. Keep the (-) plates of C_{IN} and C_{OUT} as close as possible.

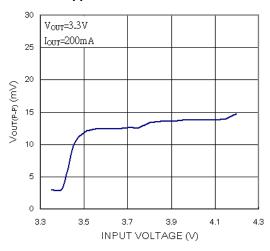


Applications (continued)

Output Voltage Ripple When V_{IN} Closes To V_{OUT} , EML3406 goes into LDO mode when input voltage closes to output voltage. The transition from PWM mode to LDO mode is smooth. Bottom diagram shows the relationship of output voltage ripple versus input voltage when output voltage is 3.3V and EML3406 provides 200mA load current.

resistance makes best efficiency. C_{IN} will require an RMS current rating of at least $I_{\text{LOAD(MAX)}}/2$ and low ESR. In most cases, a ceramic capacitor will satisfy this requirement.

V_{OUT} Ripple When V_{IN} Closes To V_{OUT}



Design Example

Assume the EML3406 is used in a single lithium-ion battery-powered application. The V_{IN} range will be about 2.7V to 4.2V. Output voltage is 1.8V.

With this information we can calculate L using equation:

$$L = \frac{1}{f \cdot \Delta I_{L}} V_{OUT} \left(1 - \frac{V_{OUT}}{V_{IN}} \right)$$

Substituting $V_{OUT}=1.8V$, $V_{IN}=4.2V$, $I_L=240mA$ and f=1.5MHz in eq. 1 gives:

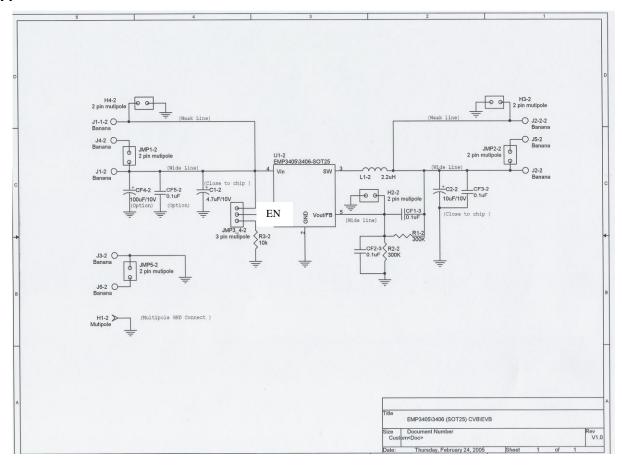
$$L = \frac{1.8 \text{V}}{1.5 \text{MHz} \cdot 240 \text{mA}} \Biggl(1 - \frac{1.8 \text{V}}{4.2 \text{V}} \Biggr) = 2.86 \mu \text{H}$$

A $2.2\mu H$ inductor could be chose with this application. A greater inductor with less equivalent series



Application (Continued)

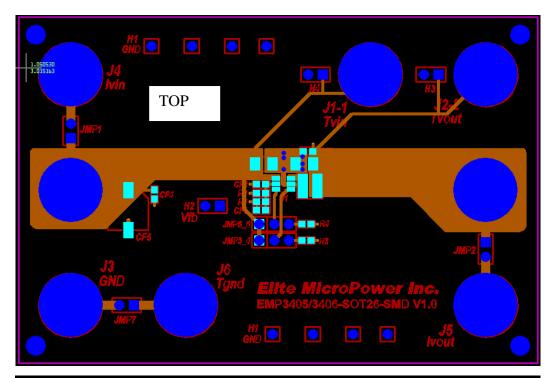
Typical schematic

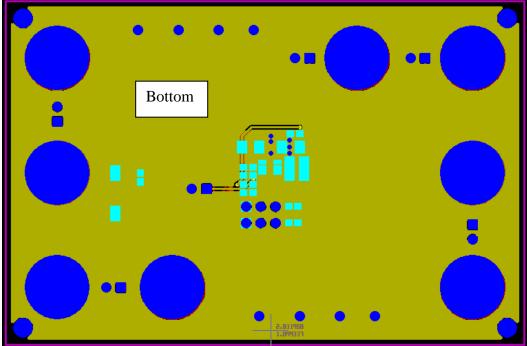




Application (Continued)

Typical PCB layout

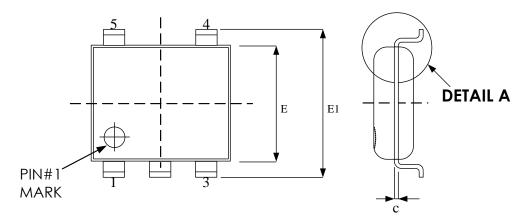




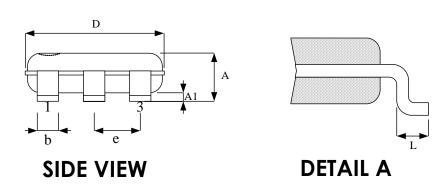


Package Outline Drawing

SOT-23-5



TOP VIEW



Cryssels of	Dimension in mm			
Symbol	Min.	Max.		
А	0.90	1.45		
A1	0.00	0.15		
ь	0.30	0.50		
С	0.08	0.25		
D	2.70	3.10		
Е	1.40	1.80		
E1	2.60	3.00		
е	0.95	BSC		
L	0.30	0.60		



Revision History

Revision	Date	Description	
8.0	2009.03.16	EMP transferred form version 7.3	
8.1	2011.01.28	Revise electrical characteristics(VEN)	
8.2	2011.03.22	Cancel the max and the min spec of ΔV_{OVL} in electrical characteristics section	
8.3	2011.05.23	Revise outline spec in Jedec dimension	
8.4	2013.04.16	Updated Vin supports to 6.0V. Removed product ID (Adj) for the marking of "A64A". Updated package outline drawing following ESMT standard.	

ESMT EML3406

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